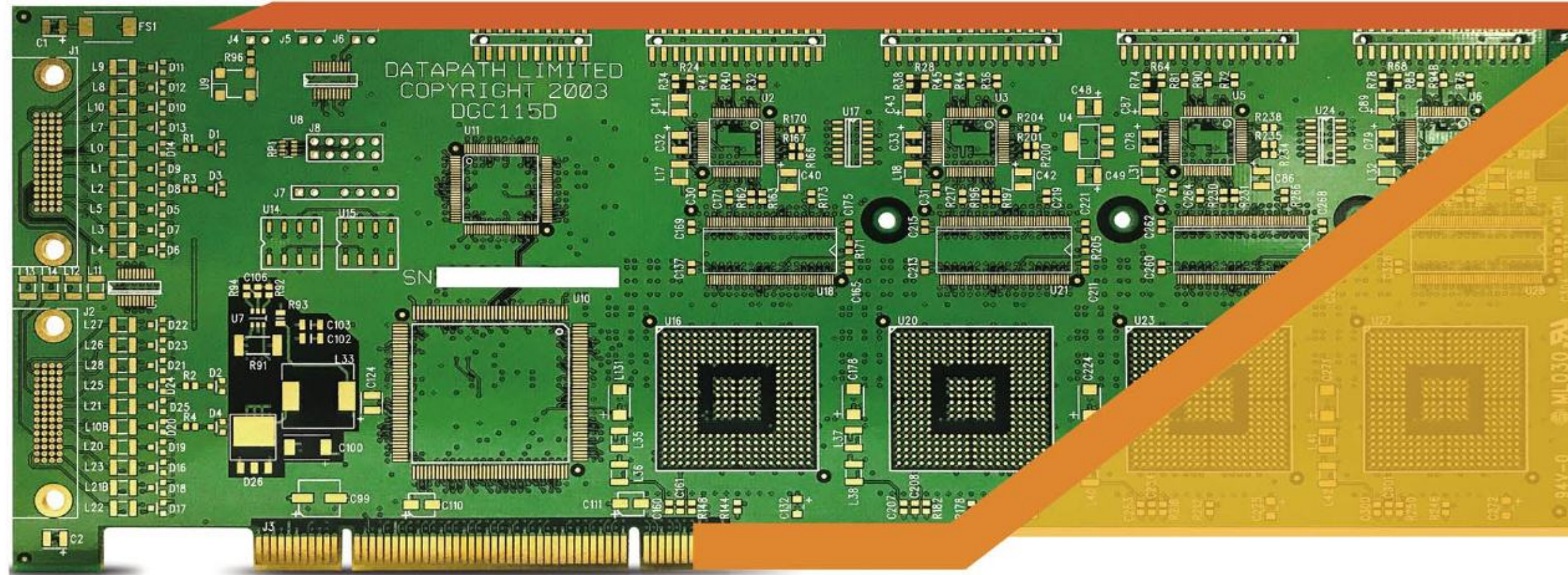


well pcb

www.wellpcb.com





COMPANY PROFILE

Focusing on PCB Prototype and PCB Assembly Turnkey Services.

WELLPCB PTY LTD, registered in Australia, is a daughter company of Uniwell Circuits Co., Ltd, which has two modern PCB factories, founded in April, 2007 . WELLPCB is Focusing on Printed Circuit Board Fabrication and PCB Assembly Turnkey Services, to meet the requirement of High Quality, Low Cost, Fast Delivery, Easy Ordering from customrs around the world. With brand new equipment and total production area over 10,000 sq. meters, WELLPCB is capable of producing 100,000 square feet of 2-32 layer PCBs and delivering over 5000 varieties monthly. We can produce quick turns to meet 24 -hour delivery for double-sided PCBs, 48-hour for 4 to 8 layers and 120-hour for 10 layers or higher PCBs.

ShenZhen UNIWELL
launched and passed UL,
ISO9001,ISO14001,TS16949

2007-2008

JiangMen UNIWELL
launched on Oct.,2010

2009-2010

JM UNIWELL passed
ISO9001,ISO14001,TS16949,
UL for mass production & monthly
capacity reach to 15000 m²

2011-2012

Upgraded all the core
equipment in SZ factory,
and monthly PN reach to 5000;
JM factory monthly capacity
reach to 25000sqm

2013-2014

Apr.2015,Registered SZ UNIWELL
technology co.,Ltd

2015

Move to new production
building E8 in Oct.,and
meanwhile monthly PN
get to 8000.JM factory
capacity reach to 30000sqm\month

2016

Monthly capacity reach to 10000 part
numbers\month in SZ factory,Average
layer count achieve to 6 layers;PCBA
and rigid & flex PCB boards production
lines planned to be finished

2017-2018

Specification	PCBA Capability
Placer speed	60000chips/hour
Lead Time	25+ Days (To Be Decided)
SMT	SMT, Through Hole Assembly Single/Double-Side SMT, Single/Double-Sides Mixture Assembly
PCB Size	50mm×50mm ~ 450mm×406mm
PCB Thickness	0.5mm ~ 4.5mm
Min. diameter / space of BGA	0.2mm/0.35mm
Qualifications	ISO 9001:2008
Accuracy	<±40µm, under the condition of 3σ, CPK≥1
Minimum width/ space of QFP	0.15mm/0.3mm, Minimum Diameter /Space of BGA: 0.2mm/0.35mm
Reliability Test	Flying Probe Test/Fixture test, Impedance Test, Solderability Test, Thermal Shock Test, Hole Resistance Test, and Micor Metallographic Section Analysis, etc.

Specification	PCB Capability
Layer Counts	1-32 layers
Lead Time	Normal: 5-6 Days Expedited: 24-Normal : 5-6Days
Materials	FR4, High TG FR4, Halogen Free material, CEM-3, Rogers HF material, etc.
Finished Copper Thickness	0.5-5 OZ
Finished Board Thickness	0.2-6.0mm
Min. Line/Track Width&Space	3mil
Qualifications	ISO 9001:2008, ISO14001:2004, ISO/TS 16949:2009 UL Certified
Technology:	On-Across Blindried Vias, Characteristic Impedance Control, Rigid-flex Board etc
Solder Mask Color:	green, black, blue, white, red, yellow, and matt, etc.
Legend/Silkscreen Color:	white, yellow, black, etc.
Surface Treatment:	HAL, Lead Free HAL, Immersion gold, OSP, Immersion tin, Immersion silver, etc.
Wrap and Twist:	≤0.7%
Other Technology:	Gold finger, peelable mask, Non-across blind-buried vias, characteristic impedance control, Rigid-flex board etc.

FPC Base Material (Adhesive)	ShengyiSF302:PI=0.5 mil,1 mil,2 mil;Cu=0.5 oz,1 oz ShengyiSF305:PI=0.5 mil,1 mil,2 mil;Cu=0.33 oz,0.5 oz,1 oz
FPC Base Material (Adhesiveless)	SongxiaRF-775/777:PI=1 mil,2 mil,3 mil;Cu=0.5 oz, 1 oz (Ultimate:PI=1 mil,2 mil,3 mil;Cu=2 oz) Xinyang:PI=1 mil, 2 mil;Cu=0.33 oz, 0.5 oz, 1 oz Taihong PI=1 mil, 2 mil;Cu=0.33 oz, 0.5 oz, 1 oz Dubang AP:PI=1 mil, 2 mil, 3 mil, 4 mil;Cu=0.5 oz, 1 oz (Ultimate:PI=1 mil, 2 mil, 3 mil, 4 mil; Cu=2 oz)
Layer	1-4 Layers (Ultimate:5-8 Layers)
Thickness of Finished Product (Flex part, no stiffener)	0.05-0.5 mm (Ultimate:0.5-0.8 mm)
Size of Finished Products (Min)	5 mm*10 mm (Bridgeless) ; 10 mm*10 mm (Bridge) Ultimate:4 mm*8 mm (Bridgeless) ; 8 mm*8 mm (Bridge)
Size of Finished Products (Max)	9 inch*14 inch Ultimate:9 inch*23 inch (PI≥1 mil)
Impedance Tolerance	Single-Ended: $\pm 5\Omega(\leq 50\Omega)$, $\pm 10\%(> 50\Omega)$ Ultimate:Single-Ended: $\pm 3\Omega(\leq 50\Omega)$, $\pm 8\%(> 50\Omega)$
Impedance Tolerance	Differential: $\pm 5\Omega(\leq 50\Omega)$, $\pm 10\%(> 50\Omega)$ Ultimate:Differential: $\pm 4\Omega(\leq 50\Omega)$, $\pm 8\%(> 50\Omega)$
Tolerance of Finger Width	± 0.1 mm (Ultimate: ± 0.05 mm)
Min Distance to the Edge of Finger	8 mil (Ultimate:6 mil)
Min Distance between Pads	4 mil (Ultimate:3 mil)
Minimum Laser Hole	0.1mm
Minimum PTH	0.3mm
Min NPTH Tolerance	± 2 mil(Ultimate +0, -2 mil or +2 mil, -0)
Solder Bridge Min Width(bottom copper <2OZ)	4 mil(Green), 8 mil
Solder Bridge Min Width(bottom copper 2-4OZ)	6 mil, 8 mil
Overlay Colour	White、Yellow (printed character:White)
Type of Surface Treatment	OSP HASL, Lead free HASL, Immersion gold, Hard gold, Immersion silver, OSP
Selective Surface Treatment	ENIG+OSP, ENIG+G/F

MAJOR EQUIPMENTS



- ① Routing Machine
- ② SolderMask Machinery
- ③ Etching Line
- ④ Automatic Character Ink Printer
- ⑤ Board Wash Cleaning Line
- ⑥ Drilling Machine
- ⑦ Dry Film Automatic

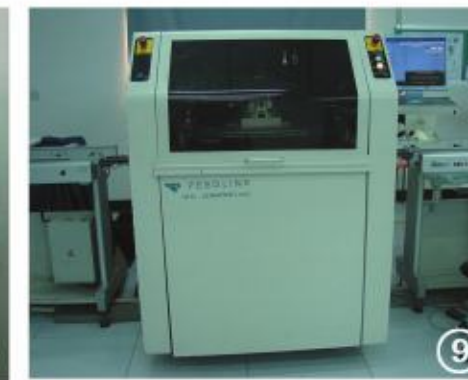


MAJOR INSPECTION EQUIPMENTS



- ① Automatic Etching
- ② Ion Contamination Testing Machine
- ③ Peeling Test Machine
- ④ Hole Copper Testing
- ⑤ AOI Both Inner&Outer Layer
- ⑥ Metallurgical Microscope
- ⑦ Hole Examination Machine
- ⑧ Flying-prototype Testing Machine





1. SMT Lines
2. Siemens F5 Multi-function Place
3. Hang Solgering Workshop
4. Siemens HS50 High Speed Placer
5. Heller1809 Reflow
6. X-ray Inspection
7. Otek Automatic Optical Inspection
8. Washing Machine
9. Speedline MPM Printer
10. BGA Repair Station

Deliverability

Shenzhen uniwell factory: 8000 types per month

Jiangmen uniwell factory: 300,000 square feet per month

Lead Time

Fastest lead time for PCB Prototype

2L: 24 hours

4-8L: 48 hours

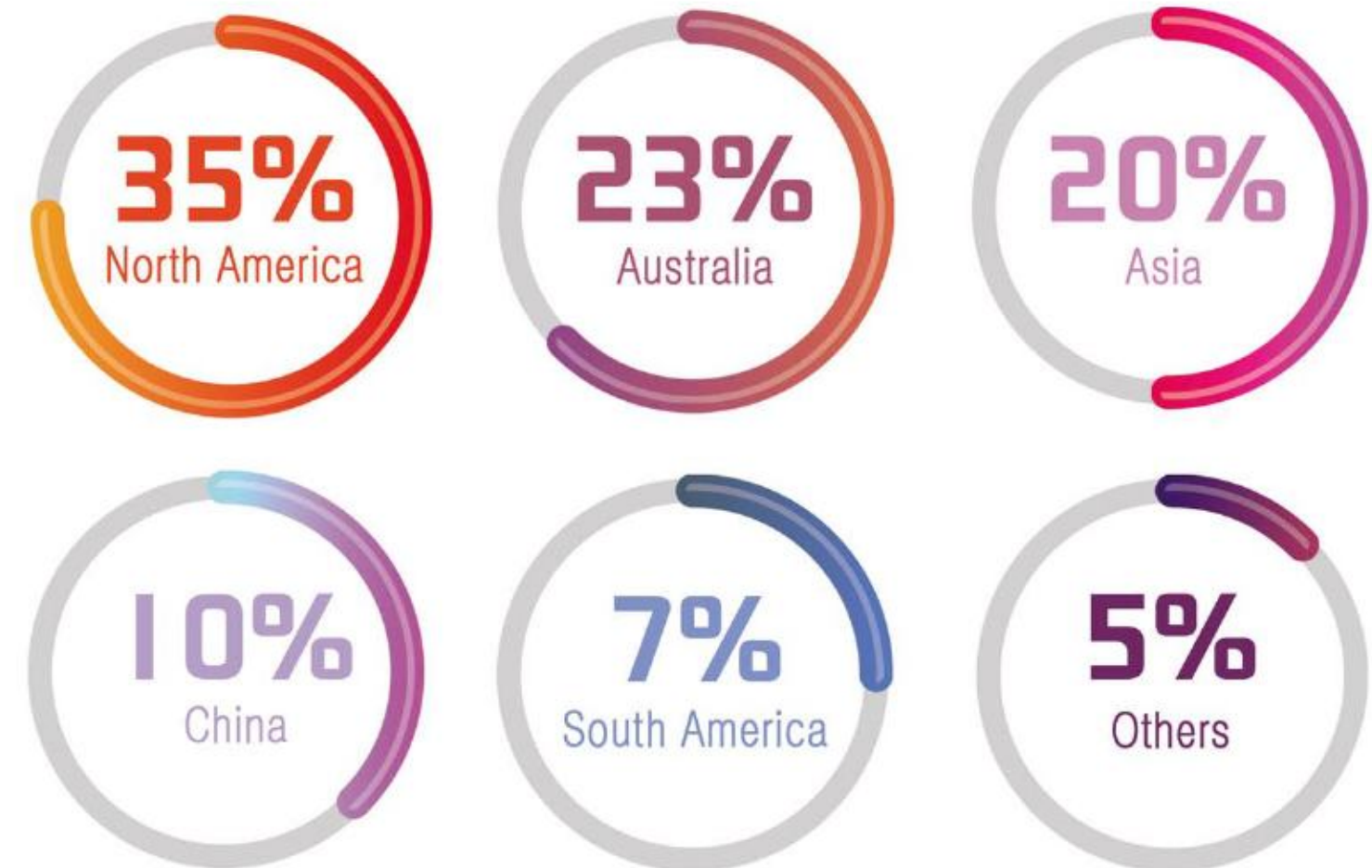
≥10L: 120 hours

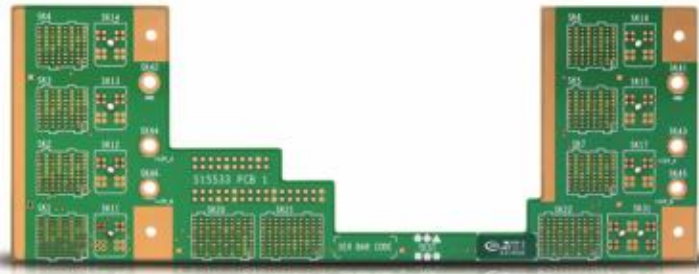
Fastest lead time for the mass production

2L: 7 working days for first batch

4-6L: 10 working days for first batch

≥8L: 12 working days for first batch





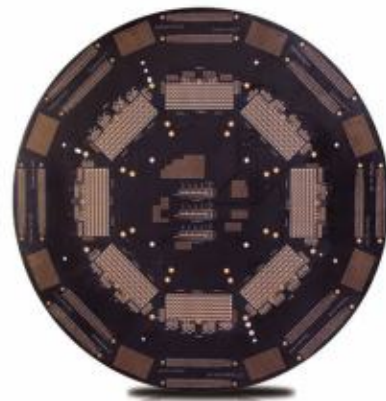
Layers	10L
Thickness	2.0mm
Min. hole size	0.2mm
Min. line width/space	3/3.5mil
Inner layer copper thickness	Hoz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.16mm



Layers	10L
Thickness	2.0mm
Min. hole size	0.2mm
Min. line width/space	4/4mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.18mm



Layers	18L
Thickness	3.0mm
Min hole size	0.25mm
Min line width	5mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min distance from hole to line	0.16mm



Layers	18L
Thickness	3.0mm
Min. hole size	0.3mm
Min. line width/space	5mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line in inner layer	0.225mm

Technical advantage the whole boards with pressing fit hole

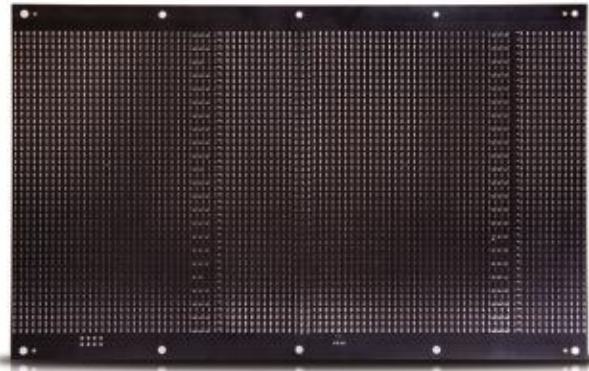


Layers	28L
Thickness	5.4mm
Min. hole size	0.3mm
Min. line width/space	3/4mil
Inner layer copper thickness	Hoz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.18mm

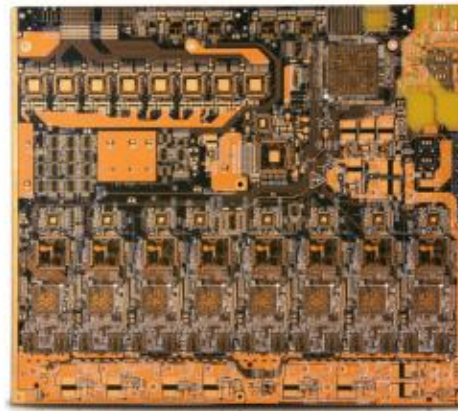
Technical advantage impedance controlled, countersink hole



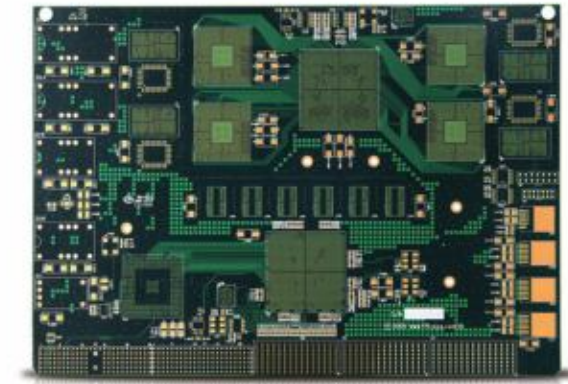
Layers	18L
Thickness	3.0mm
Min. hole size	0.25mm
Min. line width	5mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.18mm



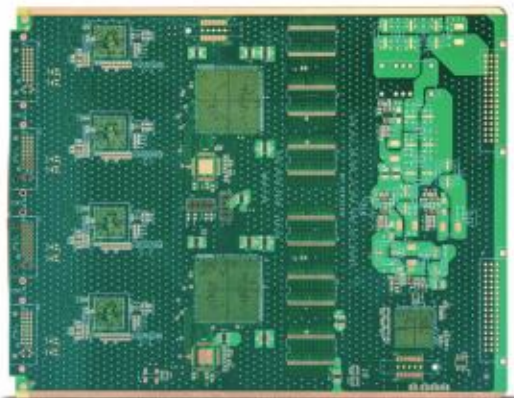
Layers	4L
Thickness	1.6mm
Min. hole size	0.2mm
Min. line width/space	4/4mil
Inner layer copper thickness	Hoz
Outer layer copper thickness	1oz
Surface finish	HASL
Min. distance from hole to line	0.15mm



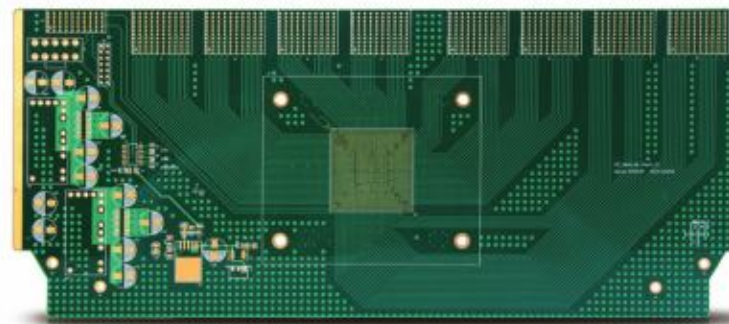
Layers	8L
Thickness	1.8mm
Min. hole size	0.2mm
Min. line width/space	3/3.5mil
Inner layer copper thickness	Hoz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.16mm



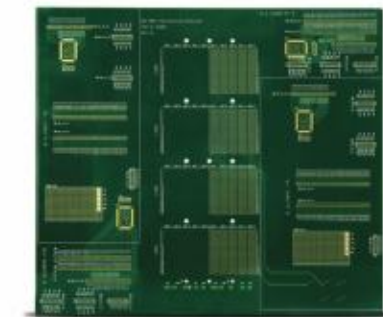
Layers	10L
Thickness	2.0mm
Min. hole size	0.2mm
Min. line width/space	4/4mil
Inner layer copper thickness	Hoz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.15mm



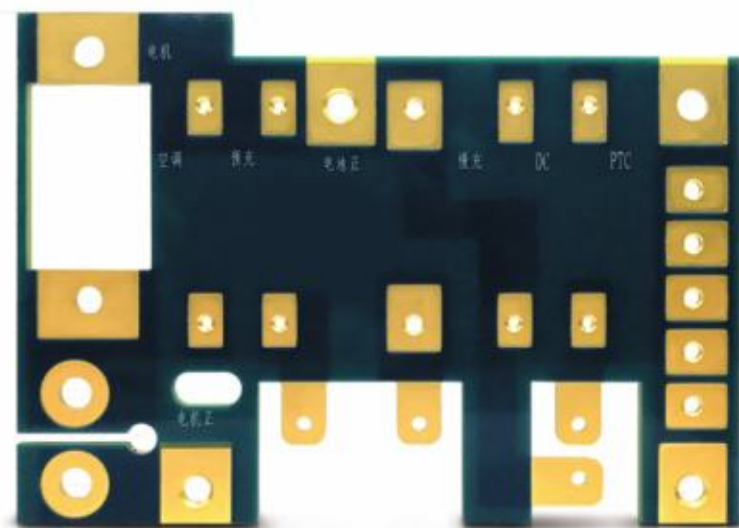
Layers	8L
Thickness	1.8mm
Min. hole size	0.2mm
Min. line width/space	3/3.5mil
Inner layer copper thickness	Hoz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.13mm



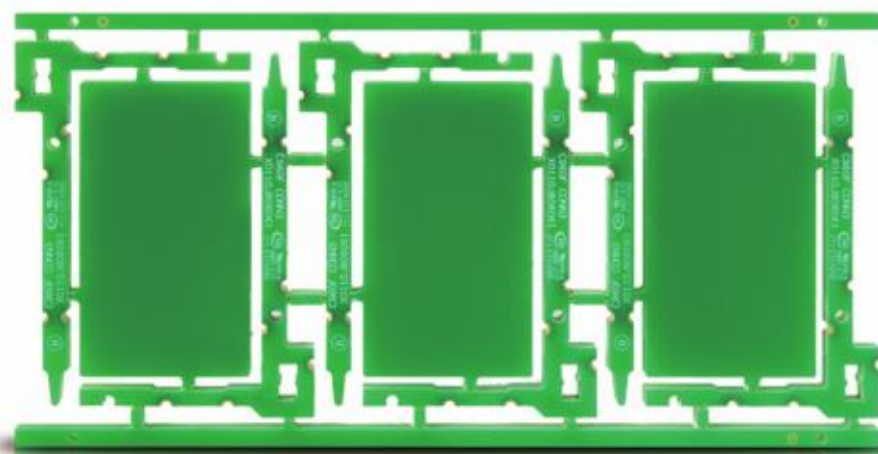
Layers	8L
Thickness	2.0mm
Min. hole size	0.2mm
Min. line width/space	4/4mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.165mm



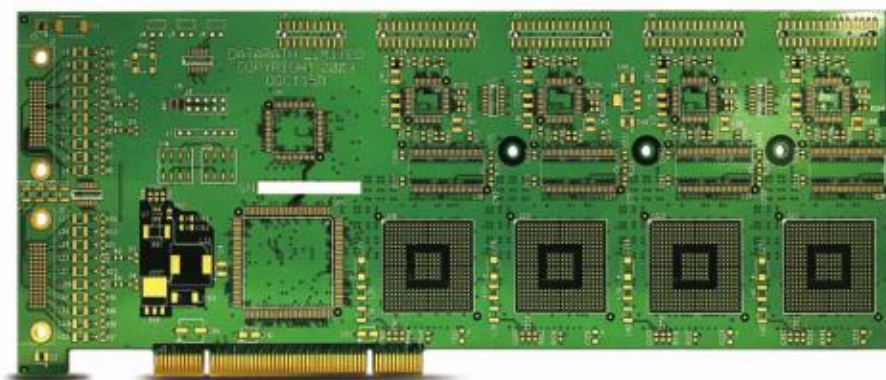
Layers	12L
Thickness	2.5mm
Min. hole size	0.3mm
Min. line width	5mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line	0.13mm



Layers 2L+
 Thickness 3.2mm
 Special technics immersion gold
 Outer layer copper thickness 6oz



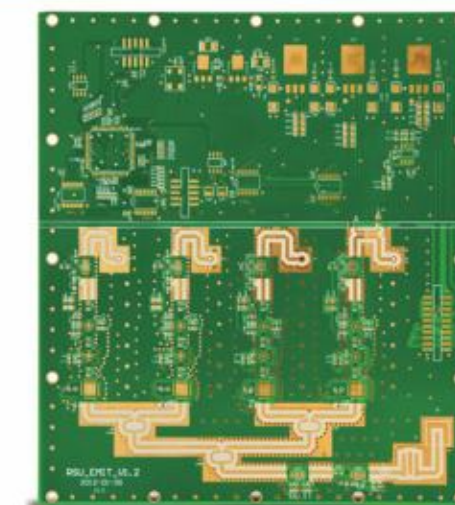
Layers 2L
 Thickness 6.0mm
 Min. hole size 0.6mm
 Outer layer copper thickness 2oz



Layers 12L
 Thickness 1.8mm
 Min. hole size 0.2mm
 Min. line width/space 3/2.5mil
 Inner layer copper thickness Hoz
 Outer layer copper thickness 1oz
 Surface finish ImmersionGold+Gold finger



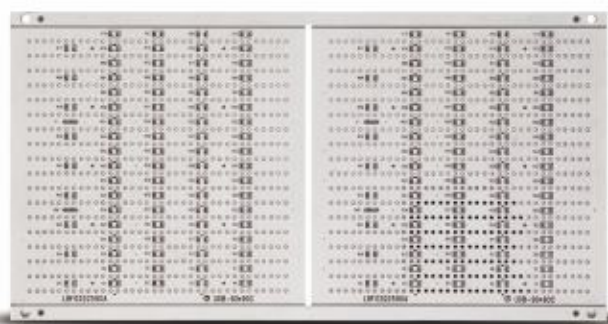
Layers 4L(Flex-rigid)
 Thickness 1.6mm
 Copper thickness 1oz
 Min. line width/space 3.5/3.5mil
 Surface treatment immersion gold



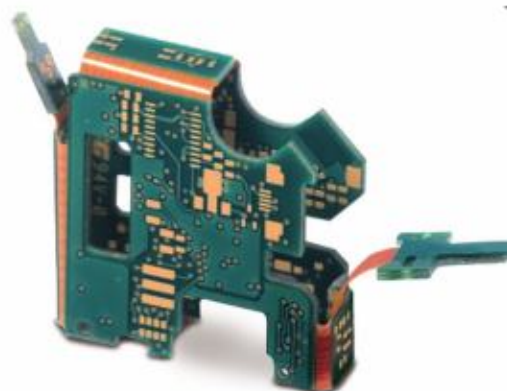
Layers 4L(Rogers+FR4)
 Thickness 1.6mm
 Min. hole size 0.2mm
 Min. line width/space 6/4mil
 Inner layer copper thickness Hoz
 Outer layer copper thickness Hoz
 Surface finish immersion gold
 Technical advantage Rogers +FR4 mixed pressing



Name Two-sided Ladder board
 Layers 8L
 Technical advantages twice buried via three times pressing
 twice plugging via with resin(exoxy)
 Buried via depth 2.3mm
 Buried hole size 0.3mm
 Ladder depth 0.95+/-0.1mm
 Distance from line to the ladder. 2.3mm



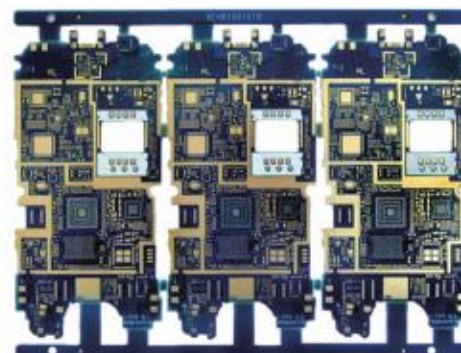
Layers	2L(Aluminum board)
Thickness	1.6mm
Min. hole size	0.2mm
Min. line width/space	5/5mil
Outer layer copper thickness	1oz
Surface finish	HASL



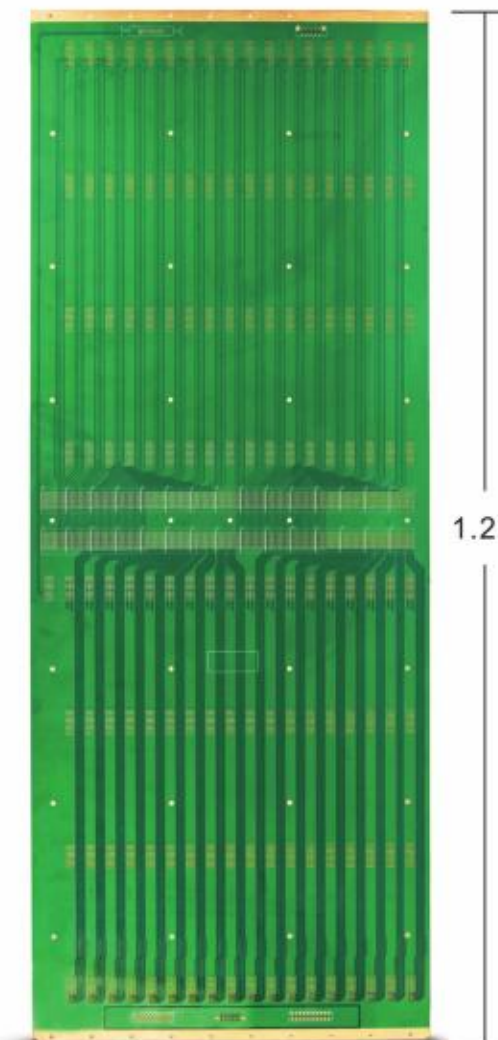
Layers	4L(Flex-rigid)
Thickness	1.6mm
Copper thickness	1oz
Min. line width/space	4/4mil
Surface treatment	immersion gold



Layers	8L(One step digital board)
Finished board thickness & tolerance	1.0+/-0.1mm
Min. line width/space	0.076mm/0.076mm
Surface finish	Immersion gold + partial BGA with OSP
Min.hole size	0.1mm



Layers	6L(two-step cellphone board)
Finished board thickness & tolerance	1.0+/-0.1mm
Min. line width/space	0.1mm/0.1mm
Surface finish	immersion gold +OSP
Min. hole size	0.1mm



Layers	16L(backplane board)
Thickness	3.0mm
Min. hole size	0.25mm
Min. line width/space	6/6mil
Inner layer copper thickness	1oz
Outer layer copper thickness	1oz
Surface finish	immersion gold
Min. distance from hole to line.	0.2mm
Product features	1.2 extra long backplane board

ISO9001



ISO14001



TS16949



UL Certificate

ZPMV2.E314500 - Wiring, Printed - Component 9E45, 1/2

ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E314500
Wiring, Printed - Component

Enhanced searching capability for this category can be found in UL's iQ Family of Databases (ul.com/iq) - View Details

Wiring, Printed - Component

See General Information for Wiring, Printed - Component E314500

SHENZHEN UNIWELL CIRCUITS CO LTD
A2 BLDG
YANCHUAN NORTH INDUSTRIAL PARK
SOUNDJIAN
SHENZHEN, GUANGDONG 518102 CHINA

Type	Cond Width		Min	Max	Hole	Area	Solder	Open	Holes	C
	Min	Max								
Multilayer printed wiring boards										
MW91	0.10 (0.004)	0.24 (0.009)	17 (0.67)	95	50.8 (2.0)	200	30	125	V-0	AF
Single layer metal base printed wiring boards										
MW92	0.10 (0.004)	0.24 (0.009)	24 (0.94)	95	50.8 (2.0)	200	28	125	V-0	AF
Single layer printed wiring boards										
MW93	0.10 (0.004)	0.24 (0.009)	17 (0.67)	95	50.8 (2.0)	200	30	125	V-0	AF

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Last updated on 2016-03-20

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GJB Certificate



Authorization Certificate

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